

PRELIMINARY AMENDMENT
National Stage Application PCT/JP2005/002345

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph no. [0015] with the following rewritten paragraph:

[0001]

The method of the present invention for controlling a high-frequency switching module comprising a diplexer comprising first and second filter circuits F1, F2 for dividing signals received by an antenna to a receiving signal of a first transmitting/receiving system and a receiving signal of second and third transmitting/receiving systems, a first switching circuit SW1 disposed downstream of the first filter circuit F1 for switching a transmitting circuit TX1 and a receiving circuit RX1 of the first transmitting/receiving system by voltage applied from a control circuit VC1, and a second switching circuit SW2 disposed downstream of the second filter circuit F2 for switching a transmitting circuit TX2 of the second and third transmitting/receiving systems, a receiving circuit RX2 of the second transmitting/receiving system and a receiving circuit RX3 of the third transmitting/receiving system by voltage applied from control circuits VC2, VC3, the method comprising applying a positive voltage from the control circuit VC1 to the first switching circuit SW1 to connect the transmitting circuit TX1 of the first transmitting/receiving system to the antenna, and applying a positive voltage from the control circuit VC3 of the second switching circuit SW2.

Please replace paragraph no. [0023] with the following rewritten paragraph:

[0002].

While the selection of one mode is conducted by voltage control by one control circuit in a conventional control method of a high-frequency switching module, the control method of a high-frequency switching module according to the present invention carries out the selection of one mode by applying voltage from control circuits of two switching circuits, for instance,

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EGSM and DCS/PCS. Namely, the control method of the present invention conducts voltage control from both directions. ~~Referring to Table 1~~Referring to Table 2, this is a control logic in which a positive voltage is applied from a control circuit VC1 of a first switching circuit SW1 and a control circuit VC3 of a second switching circuit SW2 at the time of an EGSM TX transmitting mode. At this time, diodes (DG1, DG2) constituting the first switching circuit SW1 and diodes (DD1, DD2) controlled by one control circuit in the second switching circuit SW2 are turned on. Because a diode in an OFF state generally generates harmonic distortion, harmonics can be suppressed by turning on diodes in the second switching circuit as described above. This is one of the important features of the present invention.

Please replace paragraph no. [0054] with the following rewritten paragraph:

[0003]

With respect to the antenna switching module part in the laminate, electrode patterns for the transmission lines LL1, LL2, LL3, LH1, etc. constituting the diplexer and the lowpass filter are formed mainly on upper layers, electrode patterns for the capacitors CL1, CH1, CG6, CDP2, etc. constituting the diplexer, the switching circuits and the lowpass filters are formed mainly on intermediate layers, and electrode patterns for the transmission lines LG1, LG2, LP1, LP2, LD2, LD1, etc. constituting the switching circuits are formed mainly on lower layers. With respect to the high-frequency amplifier, electrode patterns for transmission lines constituting the first-stage matching circuit are formed mainly on upper layers, electrode patterns for capacitors constituting the first- and last-stage matching circuits are formed mainly on intermediate layers, and electrode patterns for the thermal-vias, transmission lines of the last-stage matching circuit, and voltage-supplying lines are formed mainly on lower layers. Ground electrodes G1, G2, G3, G4, G5 and

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G6 are formed on the second, third, eighth, 13th, 14th and 15th layers. It should be noted that

~~Table~~ Fig. 4 does not show all ground electrodes, transmission lines and capacitors. Parts mounted onto the laminate are, as described above, diodes DG1-DD2, transistors Q1-Q3, chip capacitors CG1, CP5, Ca5-Ca7, resistors R1-R3, etc.